

## **LISTING OF THE CLAIMS**

This listing of claims, amended as indicated below, replaces all prior versions, and listings, of claims in the application

1. (Currently Amended) A method of forming a wire bond bonding a wire to a connection pad of an electronic device, comprising the steps of forming a first stitch bond on the connection pad, [[and]] forming a second stitch bond on the connection pad that is contiguous with the first stitch bond, and then severing the wire from the second stitch bond such that wire terminates at the second stitch bond.

2. (Original) A method as claimed in claim 1, wherein the second stitch bond partially lies on the first stitch bond and partially lies on the connection pad.

3. (Original) A method as claimed in claim 1, wherein a position of the second stitch bond is offset from a position of the first stitch bond.

4. (Original) A method as claimed in claim 1, including arranging the second stitch bond such that it is oriented in a different direction relative to the orientation of the first stitch bond.

5. (Original) A method as claimed in claim 1, including arranging the second stitch bond such that it is oriented in a different direction relative to a length of wire connected to the wire bond.

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6. (Original) A method as claimed in claim 1, wherein the wire is fed from a capillary, and including the step of moving the capillary in a reverse motion direction that is different to a direction that the first stitch bond is oriented after making the first stitch bond and before making the second bond.

7. (Original) A method as claimed in claim 6, including moving the capillary in a direction that is opposite to the reverse motion direction to a second stitch bonding position to form the second stitch bond.

8. (Original) A method as claimed in claim 1, including forming an additional stitch bond on the connection pad that is contiguous with the first stitch bond and/or second stitch bond.

9. (Currently Amended) A wire bond bonding a wire to a connection pad of an electronic device, comprising a first stitch bond on the connection pad and a second stitch bond terminating on the connection pad that is contiguous with the first stitch bond, and formed such that the wire terminates at the second stitch bond.

10. (Original) A wire bond as claimed in claim 9, wherein the second stitch bond partially lies on the first stitch bond and partially lies on the connection pad.

11. (Original) A wire bond as claimed in claim 9, wherein a position of the second stitch bond is offset from a position of the first stitch bond.

12. (Original) A wire bond as claimed in claim 9, wherein the second stitch bond is oriented in a different direction relative to the orientation of the first stitch bond.

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13. (Original) A wire bond as claimed in claim 9, wherein the second stitch bond is oriented in a different direction relative to a length of wire connected to the wire bond.

14. (Original) A wire bond as claimed in claim 9, including an additional stitch bond on the connection pad that is contiguous with the first stitch bond and/or second stitch bond.

15. (Canceled).

16. (Currently Amended) A semiconductor device comprising:

~~a bond pad;~~

a wire;

a connection pad; and

a wire bond connecting the wire to the connection pad, wherein the wire bond comprises:

a first stitch bond on the connection pad and a second stitch bond terminating on the connection pad that is contiguous with the first stitch bond, and formed such that the wire terminates at the second stitch bond.